BKKT 330, BKKH 330

V_{RSM} V	V_{RRM}, V_{DRM} V	I_{TRMS} = 510 A (maximum value for continuous operation) I_{TAV} = 330 A (sin. 180; T_c = 80 °C)	
900	800	BKKT 330/08E	BKKH 330/08E
1300	1200	BKKT 330/12E	BKKH 330/12E
1700	1600	BKKT 330/16E	BKKH 330/16E
1900	1800	BKKT 330/18E	BKKH 330/18E

Thyristor / Diode Modules

BKKH 330

BKKT 330

Features

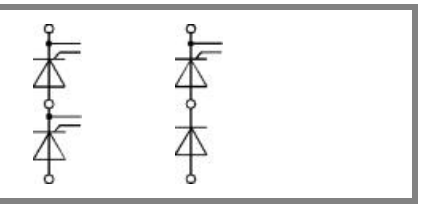
- Heat transfer through aluminium nitride ceramic isolated metal baseplate
- Precious metal pressure contacts for high reliability
- Thyristor with amplifying gate
- UL recognized, file no. E 63 532

Typical Applications*

- DC motor control (e. g. for machine tools)
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)

1) See the assembly instruction

Symbol	Conditions	Values	Units
I_{TAV}	sin. 180; T_c = 85 (100) °C;	305 (225)	A
I_D	P16/200F; T_a = 35 °C; B2 / B6	520 / 650	A
I_{RMS}	P16/200F; T_a = 35 °C; W1 / W3	585 / 3 * 485	A
I_{TSM}	T_{vj} = 25 °C; 10 ms	9500	A
	T_{vj} = 130 °C; 10 ms	8000	A
i²t	T_{vj} = 25 °C; 8,3 ... 10 ms	451000	A²s
	T_{vj} = 130 °C; 8,3 ... 10 ms	320000	A²s
V_T	T_{vj} = 25 °C; I_T = 750 A	max. 1,4	V
$V_{T(TO)}$	T_{vj} = 130 °C	max. 0,8	V
r_T	T_{vj} = 130 °C	max. 0,6	mΩ
I_{DD}; I_{RD}	T_{vj} = 130 °C; V_{RD} = V_{RRM}; V_{DD} = V_{DRM}	max. 85	mA
t_{gd}	T_{vj} = 25 °C; I_G = 1 A; di_G/dt = 1 A/µs	1	µs
t_{gr}	V_D = 0,67 * V_{DRM}	2	µs
$(di/dt)_{cr}$	T_{vj} = 130 °C	max. 250	A/µs
$(dv/dt)_{cr}$	T_{vj} = 130 °C	max. 1000	V/µs
t_q	T_{vj} = 130 °C ,	50 ... 150	µs
I_H	T_{vj} = 25 °C; typ. / max.	150 / 500	mA
I_L	T_{vj} = 25 °C; R_G = 33 Ω; typ. / max.	300 / 2000	mA
V_{GT}	T_{vj} = 25 °C; d.c.	min. 3	V
I_{GT}	T_{vj} = 25 °C; d.c.	min. 200	mA
V_{GD}	T_{vj} = 130 °C; d.c.	max. 0,25	V
I_{GD}	T_{vj} = 130 °C; d.c.	max. 10	mA
$R_{th(j-c)}$	cont.; per thyristor / per module	0,11 / 0,055	K/W
$R_{th(j-c)}$	sin. 180; per thyristor / per module	0,116 / 0,058	K/W
$R_{th(j-c)}$	rec. 120; per thyristor / per module	0,13 / 0,065	K/W
$R_{th(c-s)}$	per thyristor / per module	0,04 / 0,02	K/W
T_{vj}		- 40 ... + 130	°C
T_{stg}		- 40 ... + 130	°C
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 / 3000	V~
M_s	to heatsink	5 ± 15 %[1)]	Nm
M_t	to terminals	9 ± 15 %	Nm
a		5 * 9,81	m/s²
m	approx.	600	g
Case	SKKT	A 73b	
	SKKH	A 76b	



BKKT BKKH

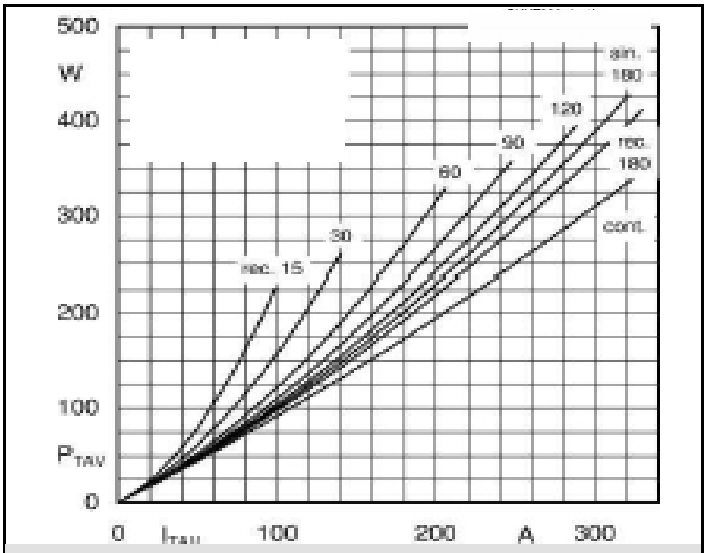


Fig. 1L Power dissipation per thyristor vs. on-state current

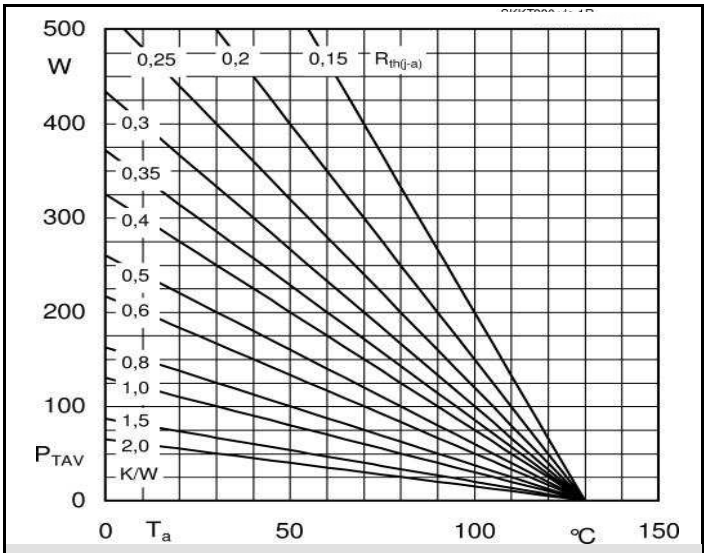


Fig. 1R Power dissipation per thyristor vs. ambient temp.

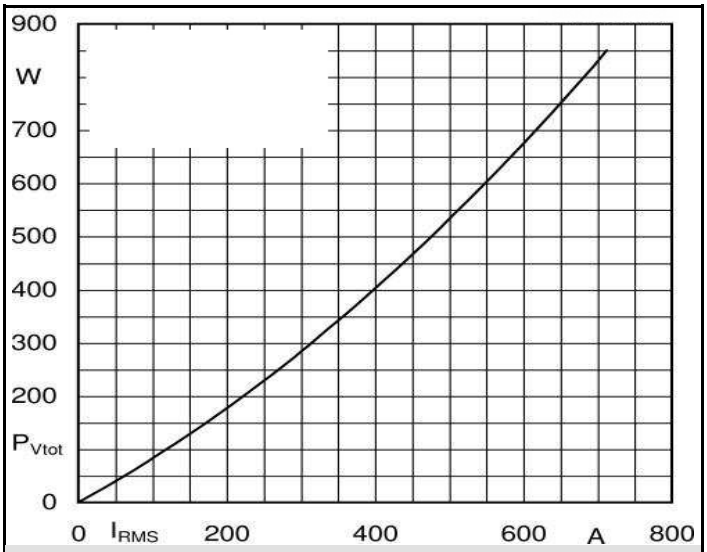


Fig. 2L Power dissipation per module vs. rms current

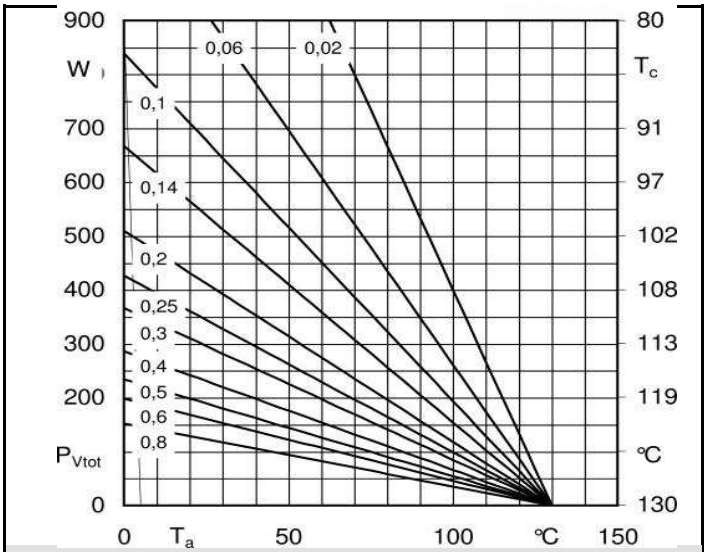


Fig. 2R Power dissipation per module vs. case temp.

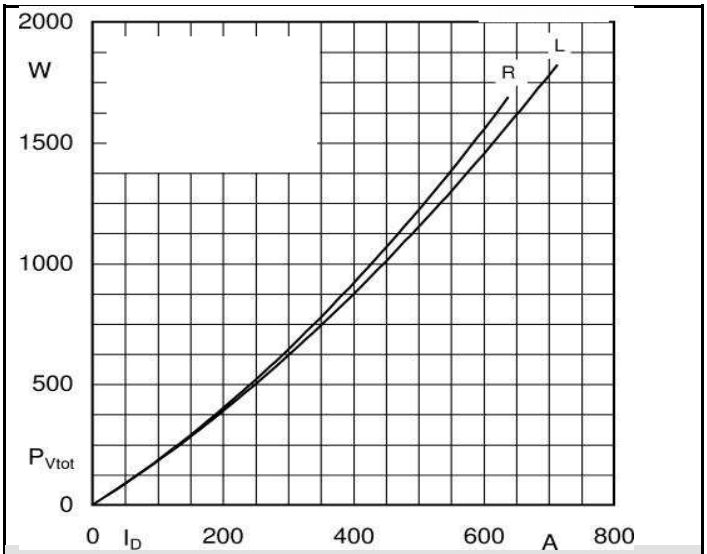


Fig. 3L Power dissipation of two modules vs. direct current

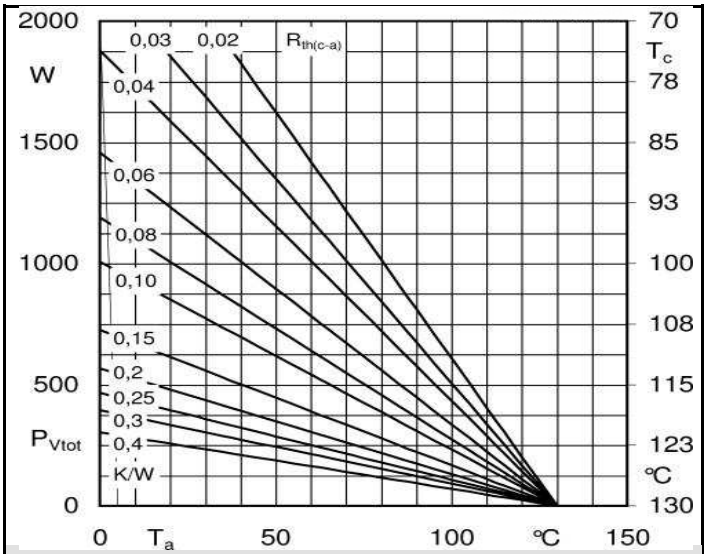


Fig. 3R Power dissipation of two modules vs. case temp.

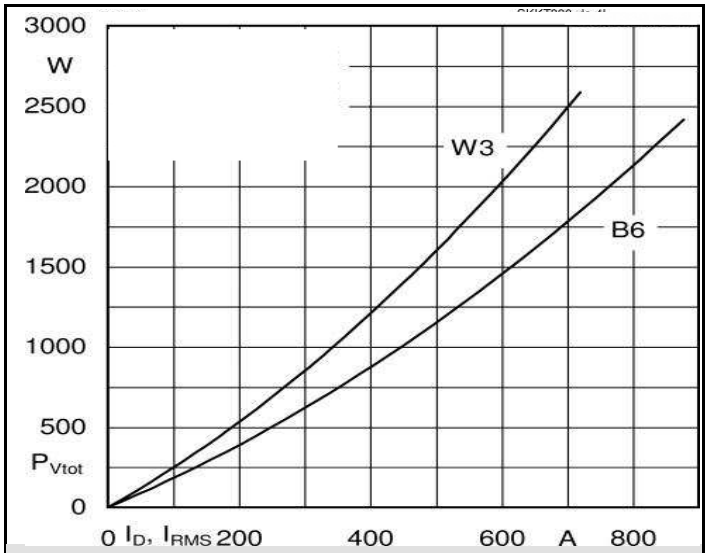


Fig. 4L Power dissipation of three modules vs. direct and rms current

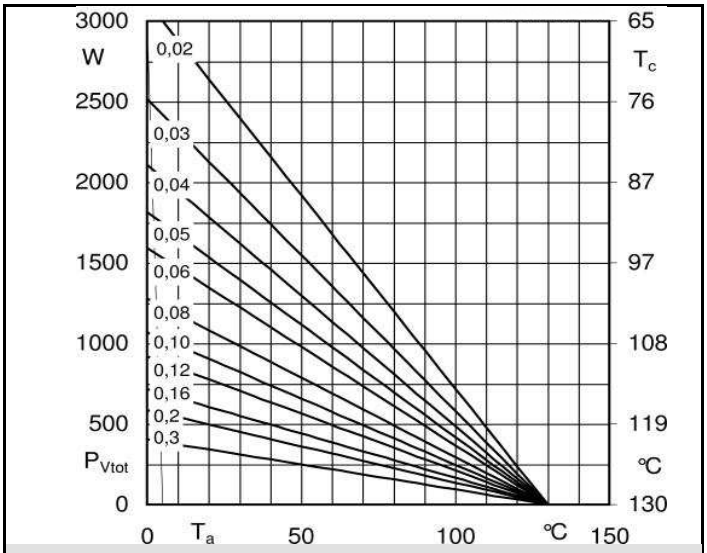


Fig. 4R Power dissipation of three modules vs. case temp.

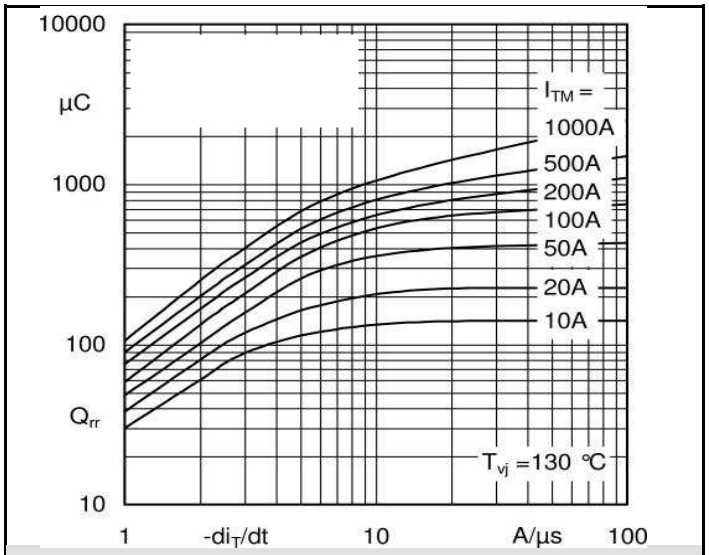


Fig. 5 Recovered charge vs. current decrease

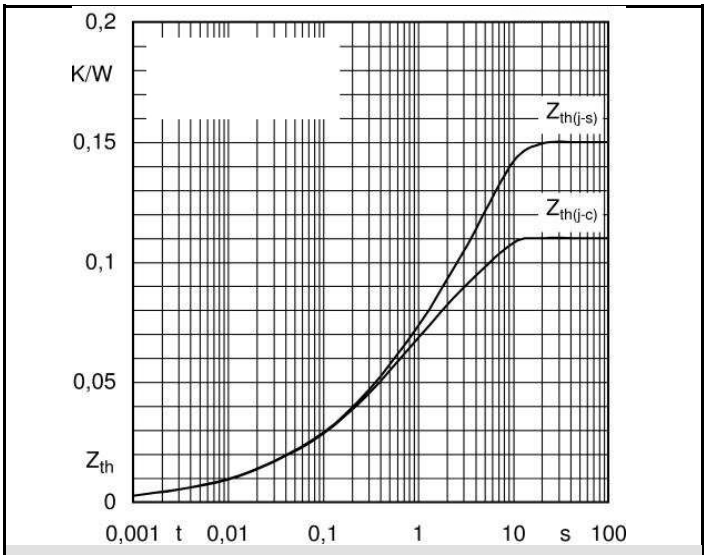


Fig. 6 Transient thermal impedance vs. time

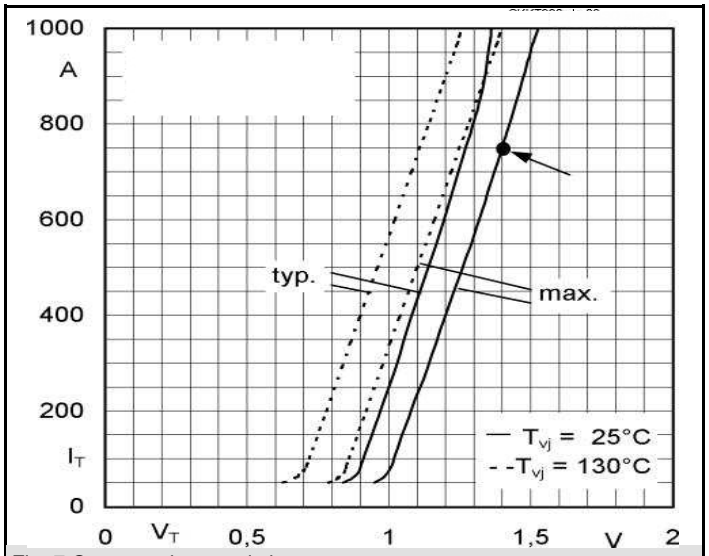


Fig. 7 On-state characteristics

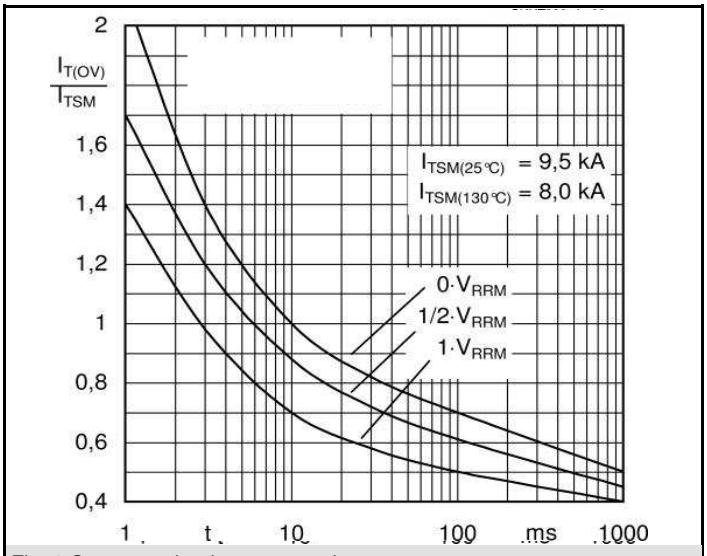


Fig. 8 Surge overload current vs. time

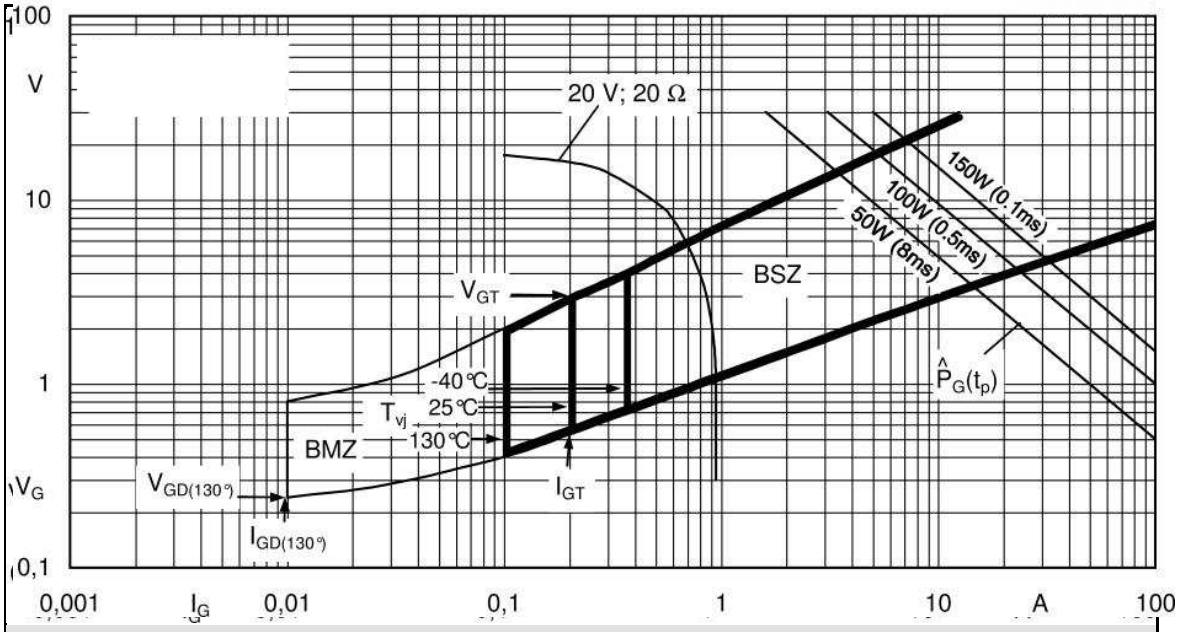
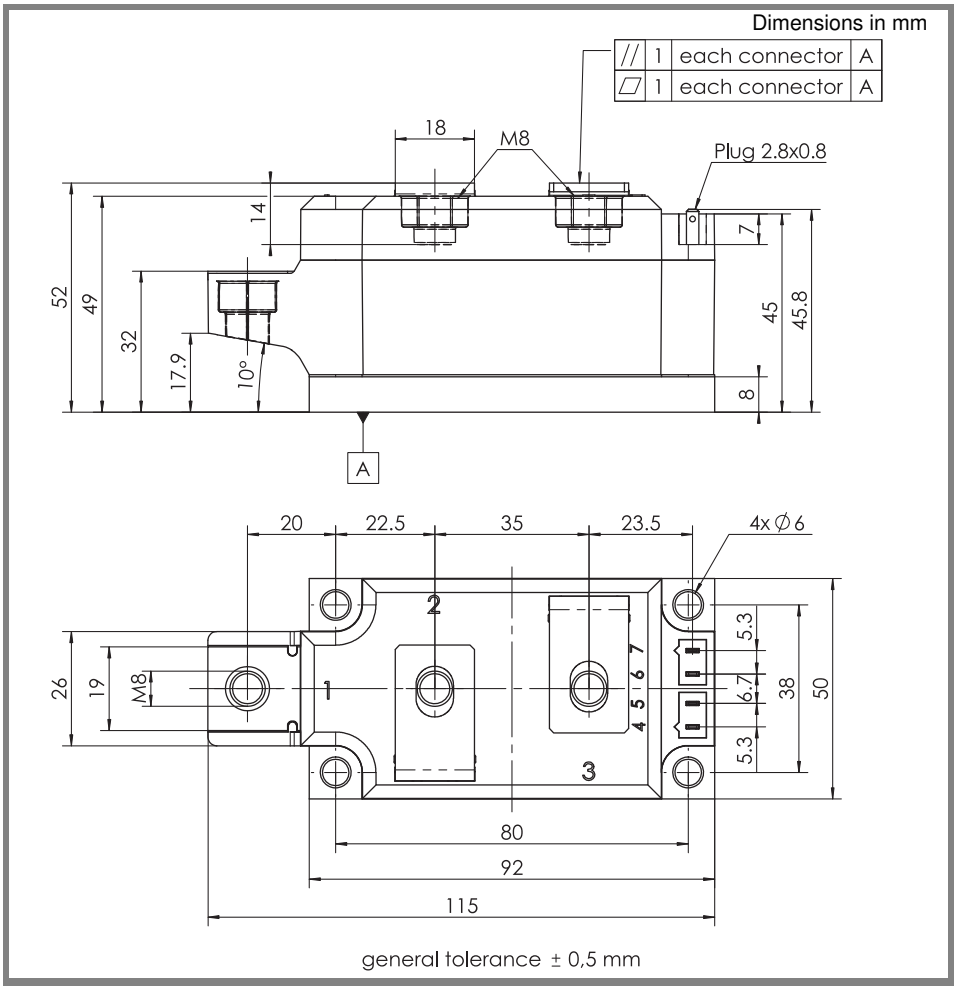
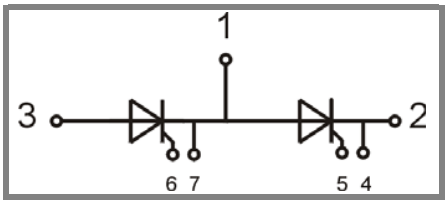


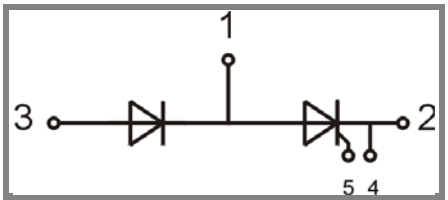
Fig. 9 Gate trigger characteristics



Semipack 3



BKKT



BKKH

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

***IMPORTANT INFORMATION AND WARNINGS**

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